

**REMARKS**

Claims 11-18 and 23-25 are pending in this application.

By this Amendment, claims 1-10, 21 and 22 are canceled and claims 19 and 20 are withdrawn due to the finality of the Restriction and Election of Species Requirement.

Claims 11 and 23 are amended and new claims 24 and 25 are added to recite additional features disclosed in the specification at, for example, Fig. 1 and page 10, lines 5-10.

Reconsideration of the application in light of the foregoing claim amendments and the following remarks is respectfully requested.

The Office Action rejects claims 11-17 and 23 under 35 U.S.C. §103(a) over U.S. Patent 6,891,248 to Akram et al. ("Akram") in view of U.S. Patent 6,323,542 to Hashimoto ("Hashimoto") and U.S. Patent 6,534,386 to Irie ("Irie"); and rejects claim 18 under 35 U.S.C. §103(a) over Akram in view of Hashimoto and Irie, and further in view of U.S. Patent 6,242,156 to Teng ("Teng"). These rejections are respectfully traversed.

The Office Action acknowledges that Akram does not disclose or suggest forming a second resin layer over a first resin layer so as to cover a side surface of the first resin layer, but asserts that Hashimoto discloses such a feature. However, Hashimoto does not disclose or suggest forming a second resin layer over the first resin layer and on the semiconductor wafer so as to cover the side surface of the first resin layer, as recited in claims 11 and 23.

Hashimoto discloses forming a supplementary transmission layer 53 over a stress relieving layer 57. See Fig. 8, and col. 11, line 65 – col. 12, line 7. See also Fig. 3, and col. 9, lines 15-36. However, Hashimoto only discloses that the supplementary transmission layer 53 is formed on the stress relieving layer 57. Hashimoto does not disclose or suggest that the supplementary transmission layer 53 is formed on the semiconductor chip 52. See Fig. 8. Thus, Hashimoto does not disclose or suggest forming a second resin layer over the first resin layer and on the semiconductor wafer so as to cover the side surface of the first

resin layer, as recited in claims 11 and 23. Hence, Hashimoto does not supply the subject matter lacking in Akram.

Irie and Teng do not disclose or suggest forming a second resin layer over the first resin layer and on the semiconductor wafer so as to cover the side surface of the first resin layer. Thus, Irie and Teng do not supply the subject matter lacking in Akram and Hashimoto.

For at least the above reasons, Akram, Hashimoto, Irie and Teng, either individually or in combination, do not disclose or suggest the subject matter recited in claims 11 and 23, and claims 12-18, depending therefrom. Accordingly, withdrawal of the rejection of claims 11-18 and 23 under 35 U.S.C. §103(a) is respectfully requested.

New claims 24 and 25 are believed to be patentable at least in view of the patentability of claims 11 and 23, from which they respectfully depend, as well as for additional features they recite.

Claims 19 and 20 are also believed to be patentable at least for the patentability of claim 11 from which they depend, as well as for additional features they recite. Accordingly, claims 19 and 20 should be rejoined.

In view of the foregoing, it is respectfully submitted that this application is in condition for allowance. Favorable reconsideration and prompt allowance of claims 11-20 and 23-25 are earnestly solicited.

Should the Examiner believe that anything further would be desirable in order to place this application in even better condition for allowance, the Examiner is invited to contact the undersigned at the telephone number set forth below.

Respectfully submitted,



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